



## Features

- 1.2kV Schottky Rectifier
- Zero Reverse Recovery Current
- High-Frequency Operation
- Temperature-Independent Switching
- Extremely Fast Switching
- Positive Temperature Coefficient on  $V_F$

## Benefits

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

## Applications

- Switch Mode Power Supplies (SMPS)
- Boost diodes in PFC or DC/DC stages
- Free Wheeling Diodes in Inverter stages
- AC/DC converters



TO220-2L  
Package



Part Number	Package	Marking
HC4D05120A	TO220-2L	HC4D05120A

## Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
$V_{RRM}$	Repetitive Peak Reverse Voltage	1200	V		
$V_{RSM}$	Surge Peak Reverse Voltage	1300	V		
$V_R$	DC Peak Reverse Voltage	1200	V		
$I_F$	Continuous Forward Current	19 9.5 5	A	$T_C=25^\circ\text{C}$ $T_C=135^\circ\text{C}$ $T_C=161^\circ\text{C}$	Fig. 3
$I_{FRM}$	Repetitive Peak Forward Surge Current	26 18	A	$T_C=25^\circ\text{C}$ , $t_p=10$ ms, Half Sine Pulse $T_C=110^\circ\text{C}$ , $t_p=10$ ms, Half Sine Pulse	
$I_{FSM}$	Non-Repetitive Forward Surge Current	46 36	A	$T_C=25^\circ\text{C}$ , $t_p=10$ ms, Half Sine Pulse $T_C=110^\circ\text{C}$ , $t_p=10$ ms, Half Sine Pulse	Fig. 8
$I_{FMax}$	Non-Repetitive Peak Forward Current	400 320	A	$T_C=25^\circ\text{C}$ , $t_p=10$ $\mu\text{s}$ , Pulse $T_C=110^\circ\text{C}$ , $t_p=10$ $\mu\text{s}$ , Pulse	Fig. 8
$P_{tot}$	Power Dissipation	100 43	W	$T_C=25^\circ\text{C}$ $T_C=110^\circ\text{C}$	Fig. 4
dV/dt	Diode dV/dt ruggedness	200	V/ns	$V_R=0-650\text{V}$	
$\int i^2 dt$	$i^2t$ value	10.6 6.5	$\text{A}^2\text{s}$	$T_C=25^\circ\text{C}$ , $t_p=10$ ms $T_C=110^\circ\text{C}$ , $t_p=10$ ms	
$T_J$	Operating Junction Range	-55 to +175	$^\circ\text{C}$		
$T_{stg}$	Storage Temperature Range	-55 to +135	$^\circ\text{C}$		
	TO220-2L Mounting Torque	1 8.8	Nm lbf-in	M3 Screw 6-32 Screw	



### Electrical Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$V_F$	Forward Voltage	1.4 1.9	1.8 3	V	$I_F = 5\text{ A } T_J = 25^\circ\text{C}$ $I_F = 5\text{ A } T_J = 175^\circ\text{C}$	Fig. 1
$I_R$	Reverse Current	20 40	150 300	$\mu\text{A}$	$V_R = 1200\text{ V } T_J = 25^\circ\text{C}$ $V_R = 1200\text{ V } T_J = 175^\circ\text{C}$	Fig. 2
$Q_C$	Total Capacitive Charge	27		nC	$V_R = 800\text{ V}, I_F = 5\text{ A}$ $di/dt = 200\text{ A}/\mu\text{s}$ $T_J = 25^\circ\text{C}$	Fig. 5
C	Total Capacitance	390 27 20		pF	$V_R = 0\text{ V}, T_J = 25^\circ\text{C}, f = 1\text{ MHz}$ $V_R = 400\text{ V}, T_J = 25^\circ\text{C}, f = 1\text{ MHz}$ $V_R = 800\text{ V}, T_J = 25^\circ\text{C}, f = 1\text{ MHz}$	Fig. 6
$E_C$	Capacitance Stored Energy	8.0		$\mu\text{J}$	$V_R = 800\text{ V}$	Fig. 7

Note: This is a majority carrier diode, so there is no reverse recovery charge.

### Thermal Characteristics

Symbol	Parameter	Typ.	Unit	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	1.5	$^\circ\text{C}/\text{W}$	Fig. 9

### Typical Performance

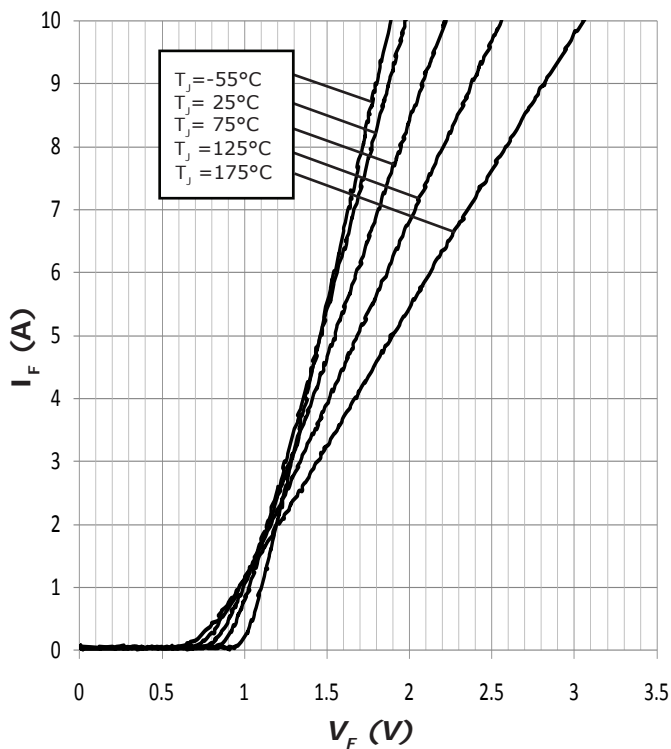


Figure 1. Forward Characteristics

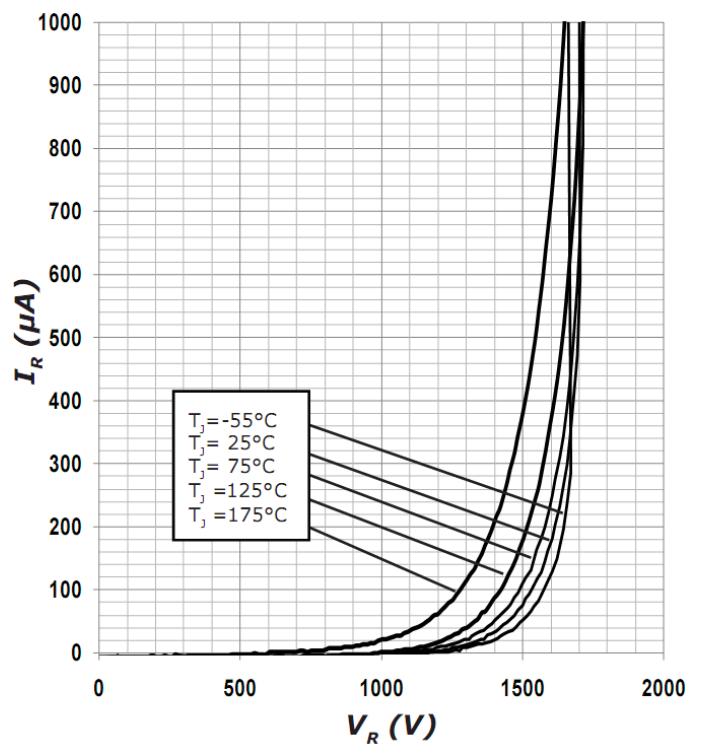


Figure 2. Reverse Characteristics



### Typical Performance

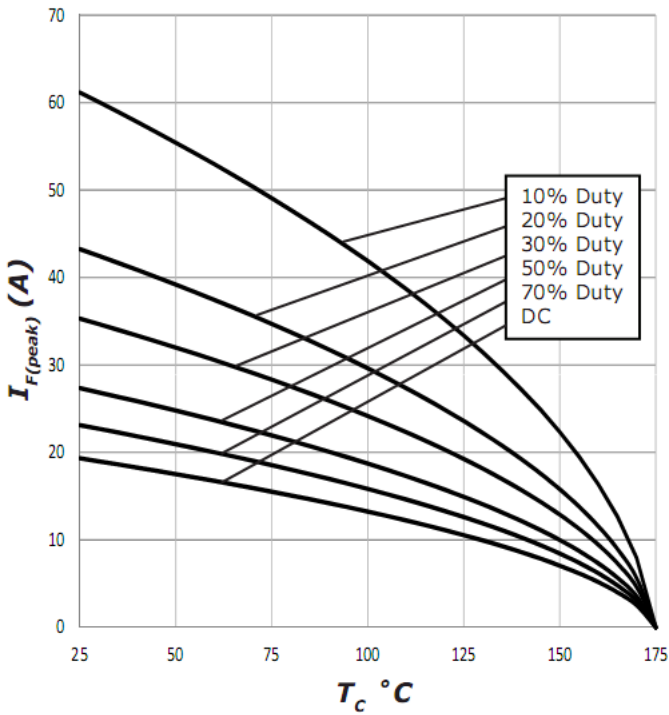


Figure 3. Current Derating

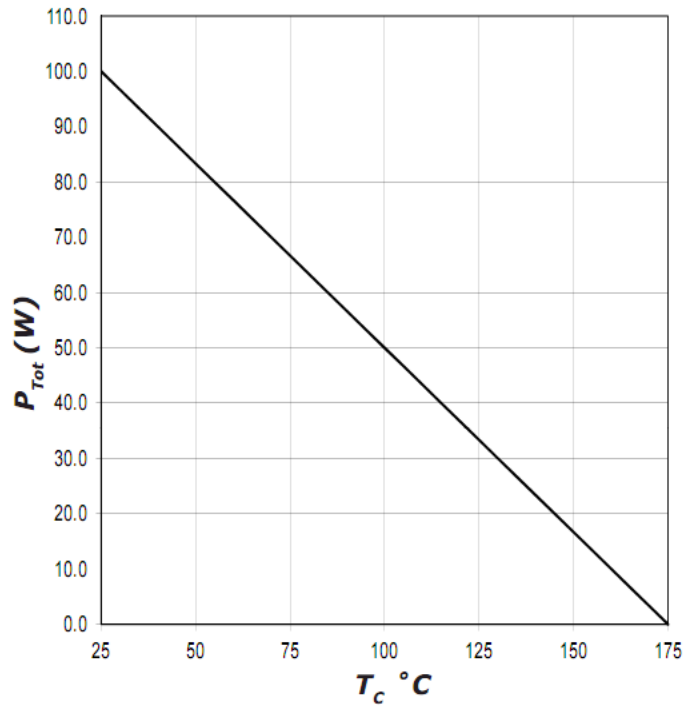


Figure 4. Power Derating

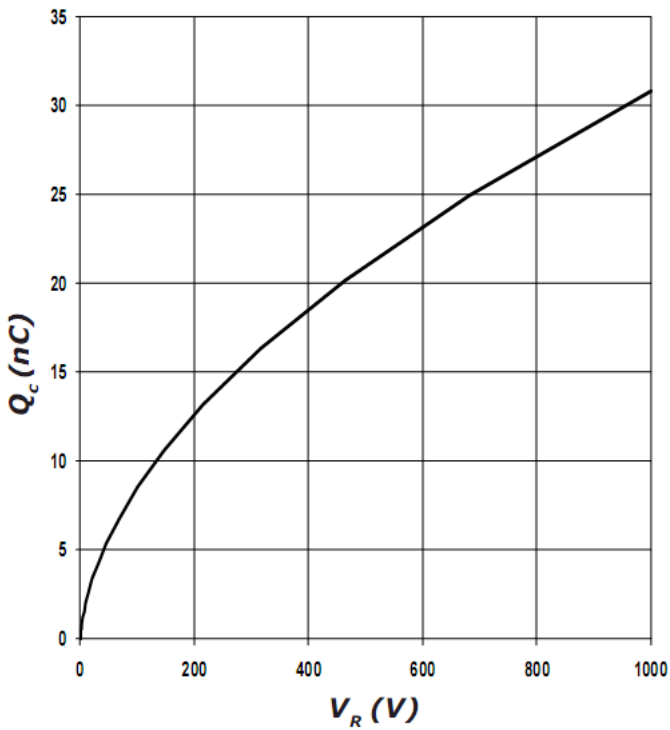


Figure 5. Recovery Charge vs. Reverse Voltage

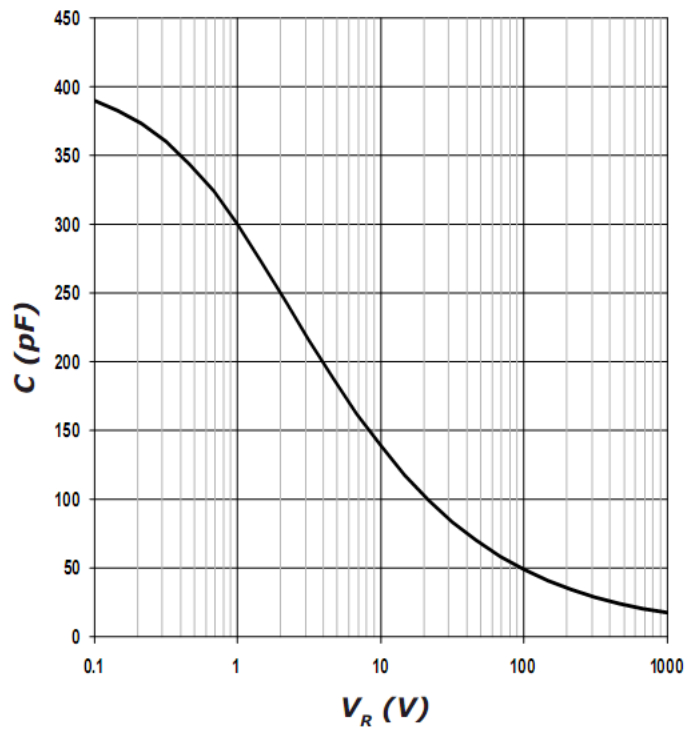
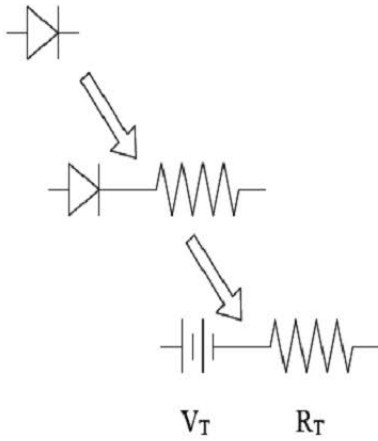


Figure 6. Capacitance vs. Reverse Voltage



## Diode Model



$$V_{f_T} = V_T + I_f * R_T$$

$$V_T = 0.96 + (T_j * -1.22 * 10^{-3})$$

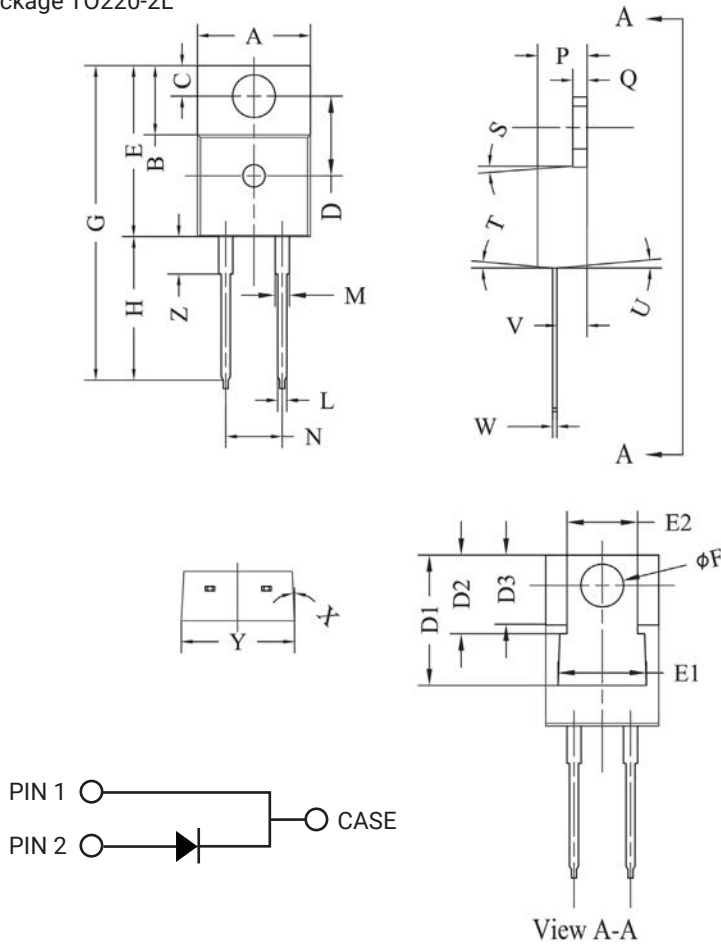
$$R_T = 0.08 + (T_j * 8.5 * 10^{-4})$$

**Note:**  $T_j$  is diode junction temperature in degrees Celsius



### Package Dimensions

Package T0220-2L

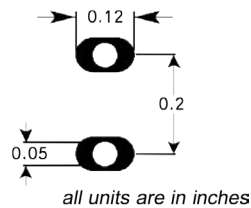


POS	Inches		Millimeters	
	Min	Max	Min	Max
A	.381	.410	9.677	10.414
B	.235	.255	5.969	6.477
C	.100	.120	2.540	3.048
D	.223	.337	5.664	8.560
D1	.457-.490		11.60-12.45 typ	
D2	.277-.303 typ		7.04-7.70 typ	
D3	.244-.252 typ		6.22-6.4 typ	
E	.590	.615	14.986	15.621
E1	.302	.326	7.68	8.28
E2	.227	.251	5.77	6.37
F	.143	.153	3.632	3.886
G	1.105	1.147	28.067	29.134
H	.500	.550	12.700	13.970
L	.025	.036	.635	.914
M	.045	.055	1.143	1.550
N	.195	.205	4.953	5.207
P	.165	.185	4.191	4.699
Q	.048	.054	1.219	1.372
S	3°	6°	3°	6°
T	3°	6°	3°	6°
U	3°	6°	3°	6°
V	.094	.110	2.388	2.794
W	.014	.025	.356	.635
X	3°	5.5°	3°	5.5°
Y	.385	.410	9.779	10.414
Z	.130	.150	3.302	3.810

NOTE:

1. Dimension L, M, W apply for Solder Dip Finish

### Recommended Solder Pad Layout



T0220-2L



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